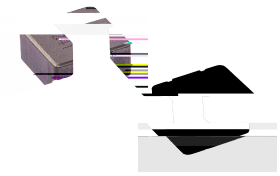
MDA Series

SMD Low Profile High Current Molded Inductor

Size 1350



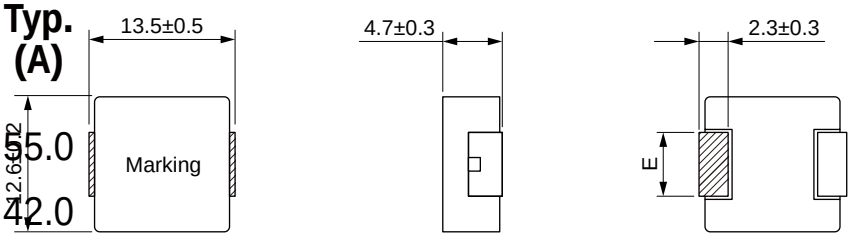
FEATURES

-
- Capable of corresponding high frequency .
- Low loss realized with low DCR.
- High performance (Isat) realized by metal dust core.
-
- 100% Lead(Pb)-Free and RoHS compliant.
-
-
-

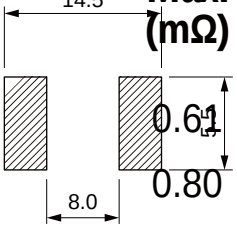
APPLICATION

-
- HVAC
-
- Audio subsystem
- Digital instrument cluster
-

Dimensions: [mm]



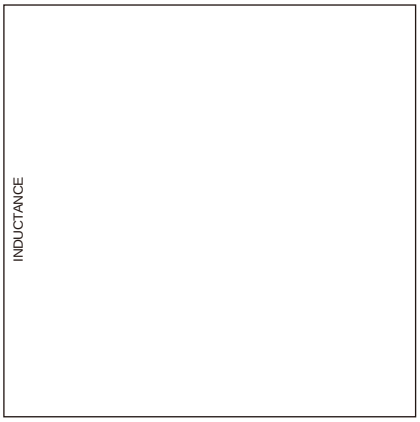
Land Pattern: [mm]

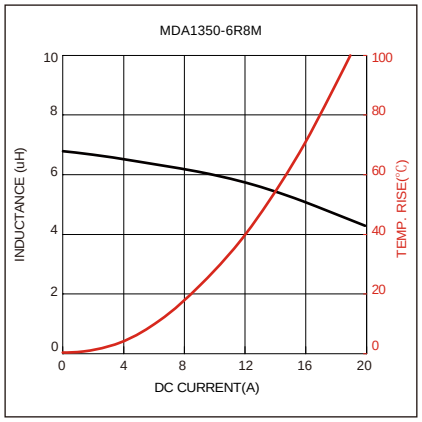


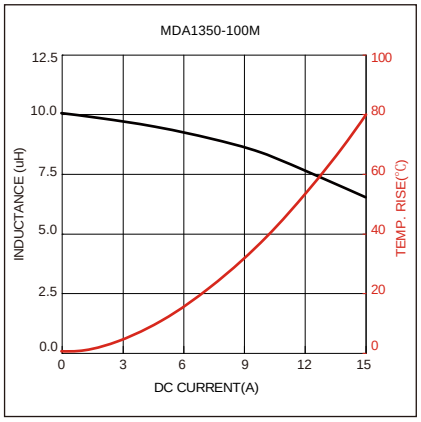
Electrical Properties:

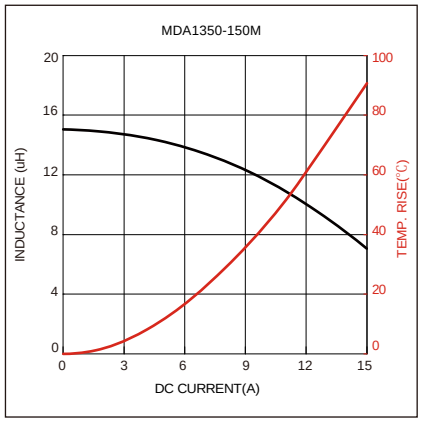
Part No	Inductance @ 100KHz/1V (µH)			Temperature Rise Current Max. (A)		Satura on Current Max. (A)			
MDA1350-R22M	0.22			50.0		60.0			
MDA1350-R33M	0.33			37.0		59.0			
MDA1350-R47M	0.47			34.0		58.0			
MDA1350-R68M	0.68			31.0		42.0			
MDA1350-1R0M	1.00			27.0		34.0			
MDA1350-1R5M	1.50	±20%	25.0	22.0	31.0	28.0	3.20	3.80	4.7±0.3
MDA1350-2R2M	2.20	±20%	17.0	15.5	26.0	23.0	4.10	4.80	4.7±0.3
MDA1350-3R3M	3.30	±20%	15.5	14.0	23.0	20.5	6.00	7.00	4.7±0.3
MDA1350-4R7M	4.70	±20%	14.0	12.5	18.5	16.0	8.80	10.2	4.7±0.3
MDA1350-6R8M	6.80	±20%	12.0	11.0	16.5	15.0	13.0	16.0	4.7±0.3
MDA1350-100M	10.0	±20%	10.0	9.0	13.0	10.5	19.2	22.0	4.7±0.3
MDA1350-150M	15.0	±20%	9.40	8.2	11.0	9.2	30.0	36.0	4.7±0.3

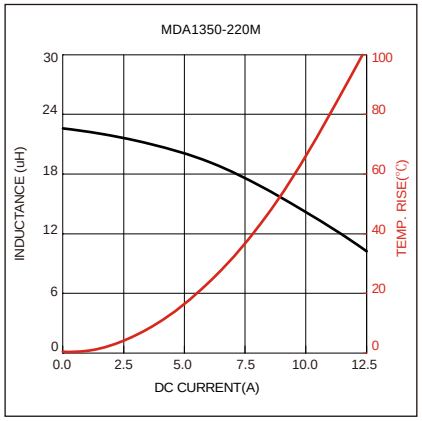
Typical Electrical Characteristics:

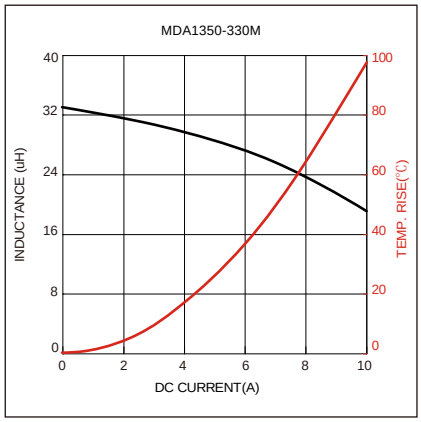


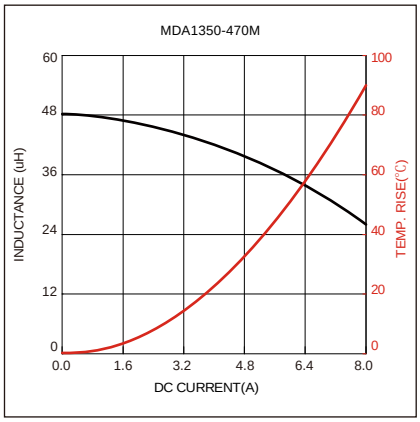

MDA1350-6R8M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 2 4 6 8 10
0 20 40 60 80 100
0 4 8 12 16 20

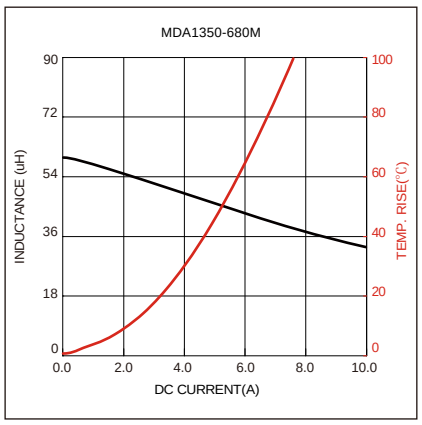

MDA1350-100M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0.0 2.5 5.0 7.5 10.0 12.5
0 20 40 60 80 100
0 3 6 9 12 15


MDA1350-150M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 4 8 12 16 20
0 20 40 60 80 100
0 3 6 9 12 15

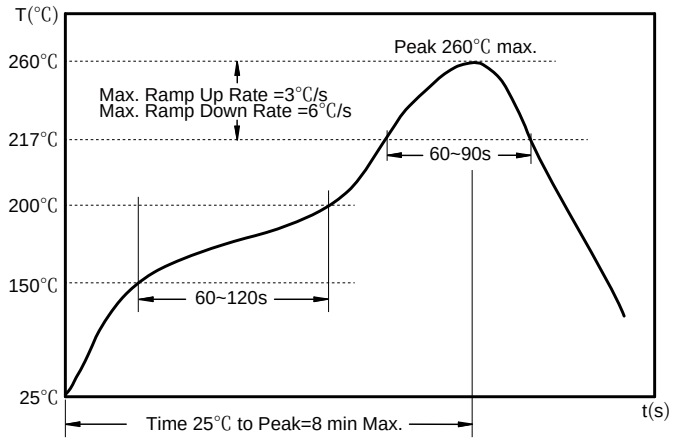

MDA1350-220M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 6 12 18 24 30
0 20 40 60 80 100
0.0 2.5 5.0 7.5 10.0 12.5


MDA1350-330M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 8 16 24 32 40
0 20 40 60 80 100
0 2 4 6 8 10


MDA1350-470M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 12 24 36 48 60
0 20 40 60 80 100
0.0 1.6 3.2 4.8 6.4 8.0


MDA1350-680M
INDUCTANCE (uH)
TEMP. RISE(℃)
DC CURRENT(A)
0 18 36 54 72 90
0 20 40 60 80 100
0.0 2.0 4.0 6.0 8.0 10.0

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~90 sec.

Max temperature: 260℃.

Max time at max temperature: 10 sec.

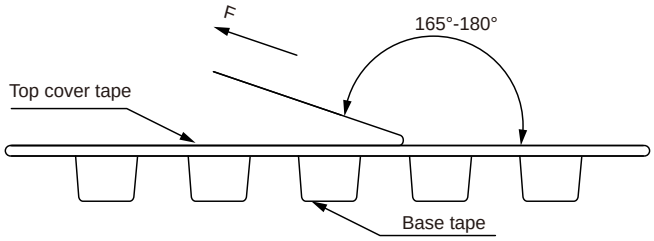
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension：

Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA1350	13.1±0.1	14.0±0.1	1.5±0.1	4.0±0.1	16.0±0.1	24.0±0.3	5.4±0.1	1.75±0.1	0.50±0.05

Peel force of top cover tape:

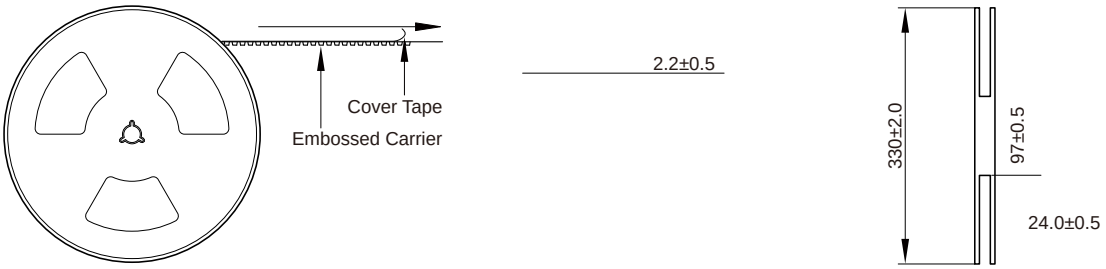


The peel force of top cover tape shall be between 0.1 to 1.3 N

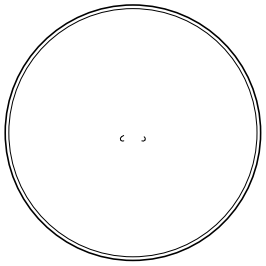
Product Marking:

Marking	KH+Printing（Inductance+period）

Reel Dimension：[mm]



Packaging Quantity:



500 Pcs/Reel

2 Reel /Inner box(1000 Pcs)

2 Inner box/Carton box(2K Pcs)

Cautions and Warnings:

Storage Conditions：

Operation Instructions: